Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	acoustic near2 wave and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing) and dummy with (opening cavity window hole trench slot groove pocket)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 14:29
1.2	177	(insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing) and dummy with (opening cavity window hole trench slot groove pocket)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 14:46
L7	187	acoustic near3 wave with filter and packag\$3 and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/18 16:04
L8	9	surface near3 wave with filter and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess)	US-PGPUB; USOCR; EPO; JPO	OR	ON	2006/01/18 16:09
L9	5	surface near3 wave with filter and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:10
L10	500	"29"/\$.ccls. and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:10
L11	173	"29"/\$.ccls. and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat\$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:13

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L12	93	"361"/\$.ccls. and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat\$3 dividing) not 11	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:15
L13	115	"438"/\$.ccls. and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat\$3 dividing) not 11 not 12	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:19
L14	139	"257"/\$.ccls. and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent\$3 excess exceed\$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat\$3 dividing) not 11 not 12 not 13	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:19
S1	1	masuko.in. and packaged.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/06 16:10
S2	3976	(base\$1board substrate board base plate) with (opening cavity window) same resin with (cover covering lid)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:13
S3	912	(base\$1board substrate board base plate) with (opening cavity window) with (ic chip semiconductor element device) same resin with (cover covering lid)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:21
S4	46	"29"/\$.ccls. and S3	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:49
S5	82	S3 and (dicing cutting singulat\$3 dividing) with (plurality individual single)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:17
S6	9	(base\$1board substrate board base plate) with (opening cavity window) with (ic chip semiconductor element device) same resin with (cover covering lid) and (dicing cutting singulat\$3 dividing) and saw near3 (chip ic filter device)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:24

						
S7	7	("20020044030" "5564181" "5699027" "5763824" "6204454" "6349870" "6467139").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:23
S8	19	(base\$1board substrate board base plate) with (opening cavity window hole) with (ic chip semiconductor element device) same resin with (cover covering sheet lid) and (dicing cutting singulat\$3 dividing) and hermetical\$3 with (seal\$4 cover\$3)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:29
S9	2578	(base\$1board substrate board base plate) with (opening cavity window hole groove pocket) with (ic chip semiconductor element device) and (insulat\$3 dielectric resin) with (cover covering sheet lid) and (dicing cutting singulat\$3 dividing) and seal\$4	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:07
S10	197	"29"/\$.ccls. and S9	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:49
S11	16	("20020092162" "20020173074" "4504435" "5998243" "6081997" "6087202" "6173490" "6200121" "6262490" "6323064" "6338813" "6383846" "6413801" "6462421" "6465277" "6519844").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:51
S12	9	(base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (acoustic near2 wave) same (cover covering sheet lid) and (dicing cutting singulat\$3 dividing) and seal\$4	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:23
S13	59	(base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (acoustic near2 wave) same (cover covering sheet lid) not S12	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:18
S14	110	(base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) same (acoustic near2 wave) same (cover covering sheet lid) not S13	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:19

S15	26	(base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) same (acoustic near2 wave) same (insulat\$3 dielectric resin\$4) with (cover covering sheet lid) and seal\$4	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:26
S16	34	(base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) same (insulat\$3 dielectric resin\$4) with (cover covering sheet lid) and seal\$4 same (acoustic near2 wave)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:28
S17	35	"438"/\$ and (base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) and (insulat\$3 dielectric resin\$4) with (cover covering sheet lid) and seal\$4 and (acoustic near2 wave)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:31
S18	461	"438"/\$ and (base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor) and (insulat\$3 dielectric resin\$4) with (cover covering sheet cap lid) and seal\$4 and (dicing cutting singulat\$3 dividing) not \$17	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:42
S19	315	S18 and (array row column)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:35
S20	193	(base\$1board substrate base\$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4) near5 (cover covering sheet cap lid) same (opening cavity window hole trench slot groove pocket) and seal\$4 same (dicing cutting singulat\$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:59

S21	74	"29"/\$.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal\$4 and (dicing cutting singulat\$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:03
S22	65	"361"/\$.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal\$4 and (dicing cutting singulat\$3 dividing) not \$21	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:05
S23	168	"438"/\$.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal\$4 and (dicing cutting singulat\$3 dividing) not \$21 not \$22	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:28
S24	97	(opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal\$4 same (dicing cutting singulat\$3 dividing) and (opening cavity window hole trench slot groove pocket) near5 (surround around circle encircle enclose inclose encompass ring)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:20
S25	22	(opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and seal\$4 same (dicing cutting singulat\$3 dividing) and surface near4 wave	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:35

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S26	6	("5484647" "5969461" "6038133" "6300686" "6310421" "6467139").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:21
S27	1	"6417574".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/17 18:34
S28	4	("5699027" "5925931" "5956606" "6137380").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:27
S29	51	("5699027").URPN.	USPAT	OR	ON	2006/01/17 18:27
S30	1	"2001110946"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/17 18:34
S31	27	(opening cavity window hole trench slot groove pocket) same (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and seal\$4 same (dicing cutting singulat\$3 dividing) and surface near4 wave	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:38
S32	16	S31 not S25	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:36
S33	5	("5459368" "5821665" "6078123" "6262513" "6310421").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:36
S34	305	(opening cavity window hole trench slot groove pocket) same (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and surface near4 wave and (seal\$4 encapsluat\$3) not \$31	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:39
S35	9	("4474685" "4883730" "5394304" "5696196" "5703761" "5918152" "5968600" "6046652" "6218610").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:41
S36	334	"438"/106-112.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:43
S37	17	"438"/\$.ccls. and acoustic near2 wave and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:47

S38	19	"333"/\$.ccls. and acoustic near2 wave and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing)	USPAT; USOCR; EPO; JPO	OR ·	ON	2006/01/18 10:57
S39	6	("5459368" "5699027" "5920142" "5991989" "6078123" "6078229").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 10:49
S40	18	("20010001740" "20010049159" "20020014687" "4778326" "5144709" "5612513" "5776798" "5801074" "5869353" "5923958" "6004833" "6222738" "6242284" "6284569" "6384472" "6428650" "6470594" "6474477").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 10:51
S41	20	("5612513").URPN.	USPAT	OR	ON	2006/01/18 10:54
S42	11	("4218701" "4502903" "4621035" "4814943" "5336931" "5350645" "5362652" "5389738" "5422514" "5477047" "5536466").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 10:56
S43	31	"257"/\$.ccls. and acoustic near2 wave and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing) not S37 not S38	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:59
S44	13	"29"/\$.ccls. and acoustic near2 wave and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing) not S37 not S38 not S43	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 11:00
S45	1	"361"/\$.ccls. and acoustic near2 wave and (insulat\$3 dielectric resin\$4 non\$1conducti\$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat\$3 dividing) not S37 not S38 not S43	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 14:28
S46	3	("5403783" "5471027" "5744863").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 11:01
S47	12	("5923958").URPN.	USPAT	OR	ON	2006/01/18 11:01